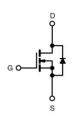
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N-channel Power MOSFET

PRODUCT SUMMARY			
V _{DS} (V) at T _J max.	650		
R _{DS(on)} max. at 25°C (Ω)	V _{GS} =10V	1.0	
Q _g max. (nC)	4	5	
Q _{gs} (nC)	-	7	
Q _{gd} (nC)	15		
Configuration	single		





TO-220F

Schematic diagram

Features

- ID=10A(Vgs=10V)
- Ultra Low Gate Charge
- Improved dv/dt Capability
- 100% Avalanche Tested
- RoHS compliant

Applications

- Switching Mode Power Supplies (SMPS)
- PWM Motor Controls
- DC to DC Converters
- LED Lighting
- Bridge Circuits

ORDERING INFORMATION				
Device	SPC10N60G			
Device Package	TO-220F			
Marking	10N60G			

ABSOLUTE MAXIMUM RATINGS (Tc = 25°C, unless otherwise noted)						
Parameter		Limit	Unit			
Drain to Source Voltage	V _{DSS}	600	V			
Continuous Drain Current (@T _C =25°C)			Α			
Continuous Drain Current (@T _C =100°C)	I _D	6.0 (1)	А			
Drain current pulsed (2)	I _{DM}	40 (1)	Α			
Gate to Source Voltage	V _{GS}	±30	V			
Single pulsed Avalanche Energy (3)	E _{AS}	400	mJ			
Peak diode Recovery dv/dt (4)	dv/dt	6	V/ns			
Total power dissipation (@T _C =25°C)	Ь	40	W			
Derating Factor above 25°C	$ P_{D}$	0.32	W/ºC			
Operating Junction Temperature & Storage Temperature			°C			
Maximum lead temperature for soldering purpose	TL	T _L 260				
Mounting torque (5)		0.4~0.6	N.m			

Notes

- 1. Drain current is limited by maximum junction temperature.
- $\ensuremath{\text{2.}} \ensuremath{\text{Repetitive rating: pulse width limited by junction temperature.}}$
- 3. L = 8mH, I_{AS} = 10A, V_{DD} = 50V, R_G =25 Ω , Starting at T_J = 25°C 4. I_{SD} ≤ 10A, di/dt = 100A/us, V_{DD} ≤ BV_{DSS}, Starting at T_J =25°C
- 5. Mounting consideration for TO220 Fullpack:

M3 screw plus flat washer is suggested, free of burr between devices and contact area, the devices are to be mounted to a hole not larger than 3.6mm in contact diameter (chamfer included).



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THERMAL CHARACTERISTICS					
Parameter	Symbol	Value	Unit		
Thermal resistance, Junction to case	R _{thjc}	3.1	°C/W		
Thermal resistance, Junction to ambient	R _{thja}	48	°C/W		

ELECTRICAL CHARACTERISTICS (Tc = 25°C unless otherwise specified)						
Parameter	Symbol	Test conditions	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain to source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	600			V
Breakdown voltage temperature coefficient	ΔBV _{DSS} / ΔTJ	I _D =250uA, referenced to 25°C		0.51		V/°C
Drain to course leakage current		V _{DS} =600V, V _{GS} =0V			1	uA
Drain to source leakage current	I _{DSS}	V _{DS} =480V, T _C =125°C			50	uA
Gate to source leakage current, forward	I _{GSS}	V _{GS} =30V, V _{DS} =0V			100	nA
Gate to source leakage current, reverse	IGSS	V _{GS} =-30V, V _{DS} =0V			-100	nA
On Characteristics						
Gate threshold voltage	$V_{GS(TH)}$	V _{DS} =V _{GS} , I _D =250uA	2		4	V
Drain to source on state resistance	R _{DS(ON)}	V _{GS} =10V, I _D =5A		0.82	1.0	Ω
Forward Transconductance	Gfs	$V_{DS} = 30 \text{ V}, I_{D} = 5 \text{A}$		7		S
Dynamic Characteristics						
Input capacitance	C _{iss}			1200		
Output capacitance	Coss	V_{GS} =0V, V_{DS} =25V, f=1MHz		125		pF
Reverse transfer capacitance	C _{rss}			21		
Turn on delay time	t _{d(on)}			15		
Rising time	tr	V_{DS} =320V, I_{D} =10A , R_{G} =25 Ω		45		ns
Turn off delay time	t _{d(off)}			90		115
Fall time	t f			30		
Total gate charge	Q_g	V _{DS} =480V, V _{GS} =10V, I _D =10A		38		
Gate-source charge	Q _{gs}			7		nC
Gate-drain charge	Q_{gd}			15		

SOURCE TO DRAIN DIODE RATINGS CHARACTERISTICS						
Parameter	Symbol	Test conditions	Min.	Тур.	Max.	Unit
Continuous source current	Is	Integral reverse p-n Junction diode in the MOSFET			10	Α
Pulsed source current	I _{SM}				40	Α
Diode forward voltage drop.	V _{SD}	I _S =10A, V _{GS} =0V			1.2	V
Reverse recovery time	T _{rr}	I _S =10A, V _{GS} =0V, dI _F /dt=100A/us		502	-	ns
Reverse recovery Charge	Qrr			13		uC



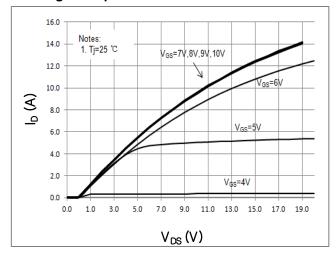


Fig3. Gate charge characteristics

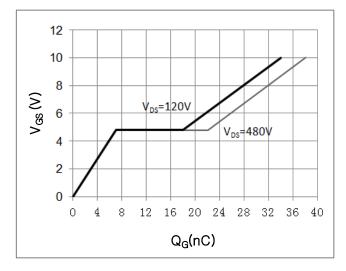


Fig 5. RDS(ON) vs junction temperature

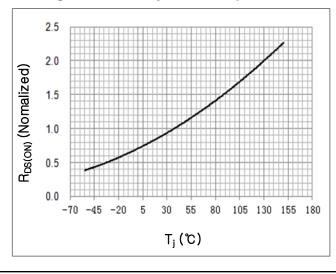


Fig2. Drain-source on-state resistance

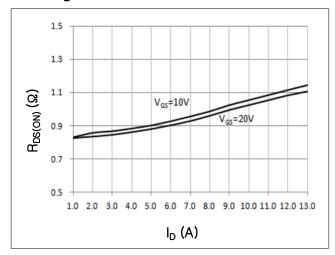


Fig 4. Capacitance Characteristics

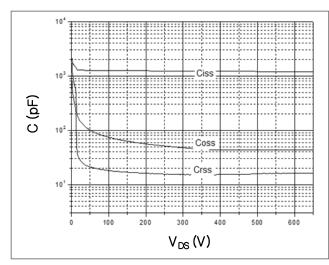
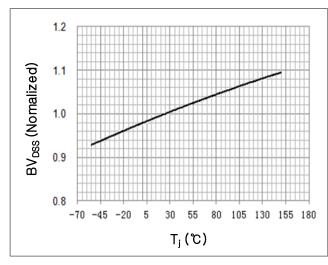


Fig 6. BVDss vs junction temperature



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Fig 7. Safe operating area

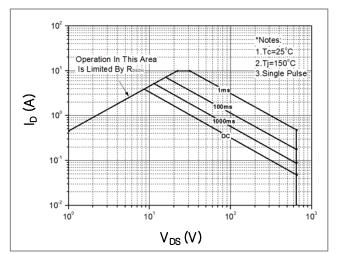


Fig 8. Transient thermal impedance

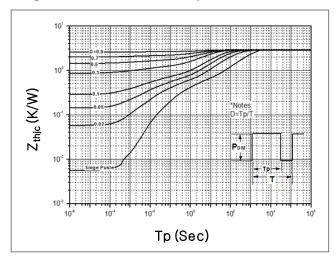


Fig 9. Forward characteristics of reverse diode

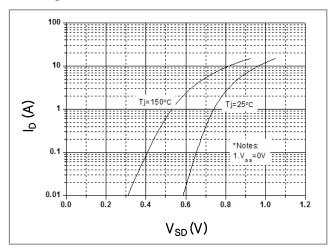
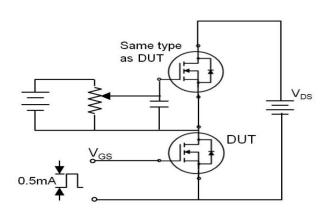
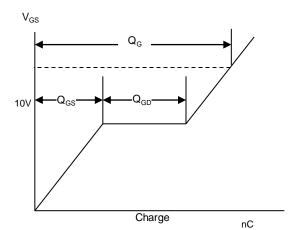


Fig 10. Gate charge test circuit & waveform





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Fig 11. Switching time test circuit & waveform

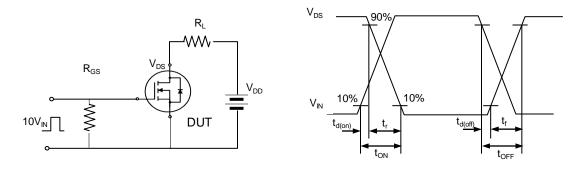


Fig 12. Unclamped Inductive switching test circuit & waveform

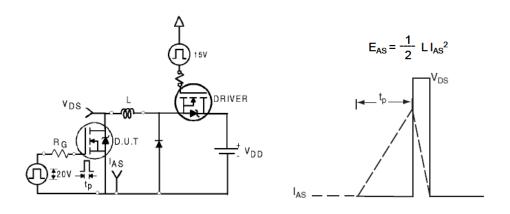
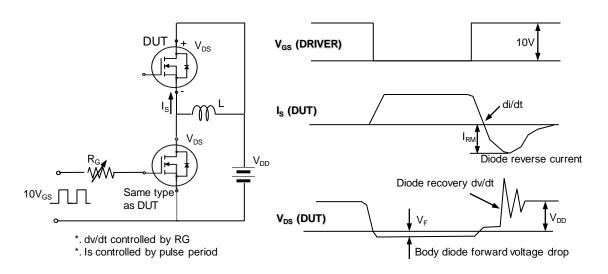


Fig 13. Peak diode recovery dv/dt test circuit & waveform



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